3.3 V 168-pin Registered SDRAM Modules

PC133 128 MByte Module
PC133 256 MByte module
PC133 512 MByte Module
PC133 1 GByte Module
PC133 2 GByte Module

- 168-pin Registered 8 Byte Dual-In-Line SDRAM Module for PC and Server main memory applications
- One bank 16M × 72, 32M x 72, 64M × 72and 128M x 72, two bank 128M × 72 and 256M x 72 organization
- Optimized for ECC applications with very low input capacitances
- JEDEC standard Synchronous DRAMs (SDRAM) Programmable $\overline{CAS}$ Latency, Burst Length and Wrap Sequence (Sequential & Interleave)
- Single + 3.3 V (± 0.3 V) power supply
- Auto Refresh (CBR) and Self Refresh
- Programmable $\overline{CAS}$ Latency, Burst Length, and Wrap Sequence (Sequential & Interleave)
- All inputs and outputs are LVTTL compatible
- Serial Presence Detect with E^2PROM
- Utilizes SDRAMs in TSOPII-54 packages with registers and PLL.
- Card Size: 133.35 mm × 38.10 / 43.18 mm with Gold contact pads and max. 4.00 / 6.80 mm thickness (JEDEC MO-161)
- These modules all fully compatible with the current industry standard PC133 and PC100 specifications
- Performance:

speed grade		-7	-7.5	Unit
f_{CK}	Clock Frequency (max.) @ CL = 3	133	133	MHz
t_{CK}	Clock Cycle Time (min.) @ CL = 3	7.5	7.5	ns
t_{AC}	Clock Access Time (min.) @ CL= 3	5.4	5.4	ns
f_{CK}	Clock Frequency (max.) @ CL = 2	133	100	MHz
t_{CK}	Clock Cycle Time (min.) @ CL = 2	7.5	10	ns
t_{AC}	Clock Access Time (min.) @ CL= 2	5.4	6	ns

Description

The HYS 72Vxx3xxGR-7 and -7.5 are industry standard 168-pin 8-byte Dual in-line Memory Modules (DIMMs) organized as 16M × 72, 32M x 72, 64M × 72, 128M × 72 and 256M x 72 high speed memory arrays designed with Synchronous DRAMs (SDRAMs) for ECC applications. All control and address signals are registered on-DIMM and the design incorporates a PLL circuit for the Clock inputs. Use of an on-board register reduces capacitive loading on the input signals but are delayed by one cycle in arriving at the SDRAM devices. Decoupling capacitors are mounted on the PC board. The DIMMs use a serial presence detects scheme implemented via a serial E^2PROM using the 2-pin I^2C protocol. The first 128 bytes are utilized by the DIMM manufacturer and the second 128 bytes are available to the end user. All Infineon 168-pin DIMMs provide a high performance, flexible 8-byte interface in a 133.35 mm long footprint.

Ordering Information

Partnumber [1]	Compliance Code [2]	Description	SDRAM Technology
PC133-333:			
HYS 72V16300GR-7.5-C HYS 72V16300GR-7.5-E	PC133R-333-542-B2	one bank 128 MB Reg. DIMM	64 MBit (x4)
HYS 72V16301GR-7.5-C2	PC133R-333-542-B2	one bank 128 MB Reg. DIMM	128 MBit (x8)
HYS 72V32301GR-7.5-C2	PC133R-333-542-B2	one bank 256 MB Reg. DIMM	128 Mbit (x4)
HYS 72V32300GR-7.5-C2 HYS 72V32300GR-7.5-D	PC133R-333-542-AA	one bank 256 MB Reg. DIMM	256 Mbit (x8)
HYS 72V64300GR-7.5-C2 HYS 72V64300GR-7.5-D	PC133R-333-542-B2	one bank 512 MB Reg. DIMM	256 MBit (x4)
HYS 72V128320/1GR-7.5-C2 HYS 72V128320/1GR-7.5-D	PC133R-333-542-B2	two banks 1 GByte Reg. DIMM	256 MBit (x4, stacked) [3]
HYS 72V128300GR-7.5-A	PC133R-333-542-B2	one bank 1 GByte Reg. DIMM	512 MBit (x4)
HYS 72V256320/1GR-7.5-A	PC133R-333-542-B2	two banks 2 GByte Reg. DIMM	512 MBit (x4, stacked) [3]
PC133-222:			
HYS 72V16300GR-7-E	PC133R-222-542-B2	one bank 128 MB Reg. DIMM	64 MBit (x4)
HYS 72V16301GR-7-C2	PC133R-222-542-B2	one bank 128 MB Reg. DIMM	128 MBit (x8)
HYS 72V32301GR-7-C2	PC133R-222-542-B2	one bank 256 MB Reg. DIMM	128 Mbit (x4)
HYS 72V32300GR-7-D	PC133R-222-542-AA	one bank 256 MB Reg. DIMM	256 Mbit (x8)
HYS 72V64300GR-7-D	PC133R-222-542-B2	one bank 512 MB Reg. DIMM	256 MBit (x4)
HYS 72V128320/1GR-7-D	PC133R-222-542-B2	two banks 1 GByte Reg. DIMM	256 MBit (x4, stacked) [3]
HYS 72V128300GR-7-A	PC133R-222-542-B2	one bank 1 GByte Reg. DIMM	512 MBit (x4)
HYS 72V256320/1GR-7-A	PC133R-222-542-B2	two banks 2 GByte Reg. DIMM	512 MBit (x4, stacked) [3]

Notes:
1.) All part numbers end with a place code, designating the die revision of the components used on the Registered DIMM module. Consult factory for current revision. Example: HYS 64V32300GR-7.5-D, indicating Rev.D dies are used for 256Mbit SDRAM components.
2.) The Compliance Code is printed on the modules labels and describes speed sort of the modules, latencies, access time from clock,SPD revision and Raw Card version acording to the actual JEDEC standard.
3.) Modules with stacked components are available in two version, with components stacked using a soldering stacking technique (f.e. HYS72V128320GR-7.5) and an welding technique developed by INFINEON Technologies (f.e. HYS72V128321GR-7.5)

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Pin Definitions and Functions

A0 - A11, A12	Address Inputs (A12 is used for 256Mbit based modules only)	DQMB0 - DQMB7	Data Mask
BA0, BA1	Bank Selects	$\overline{CS0}$ - $\overline{CS3}$	Chip Select
DQ0 - DQ63	Data Input/Output	REGE*)	Register Enable “H” or N.C = registered mode “L” = buffered mode
CB0 - CB7	Check Bits	V_{DD}	Power (+ 3.3 V)
$\overline{RAS}$	Row Address Strobe	V_{SS}	Ground
$\overline{CAS}$	Column Address Strobe	SCL	Clock for Presence Detect
$\overline{WE}$	Read/Write Input	SDA	Serial Data Out
CKE0	Clock Enable	N.C.	No Connection
CLK0 - CLK3	Clock Input	–	–

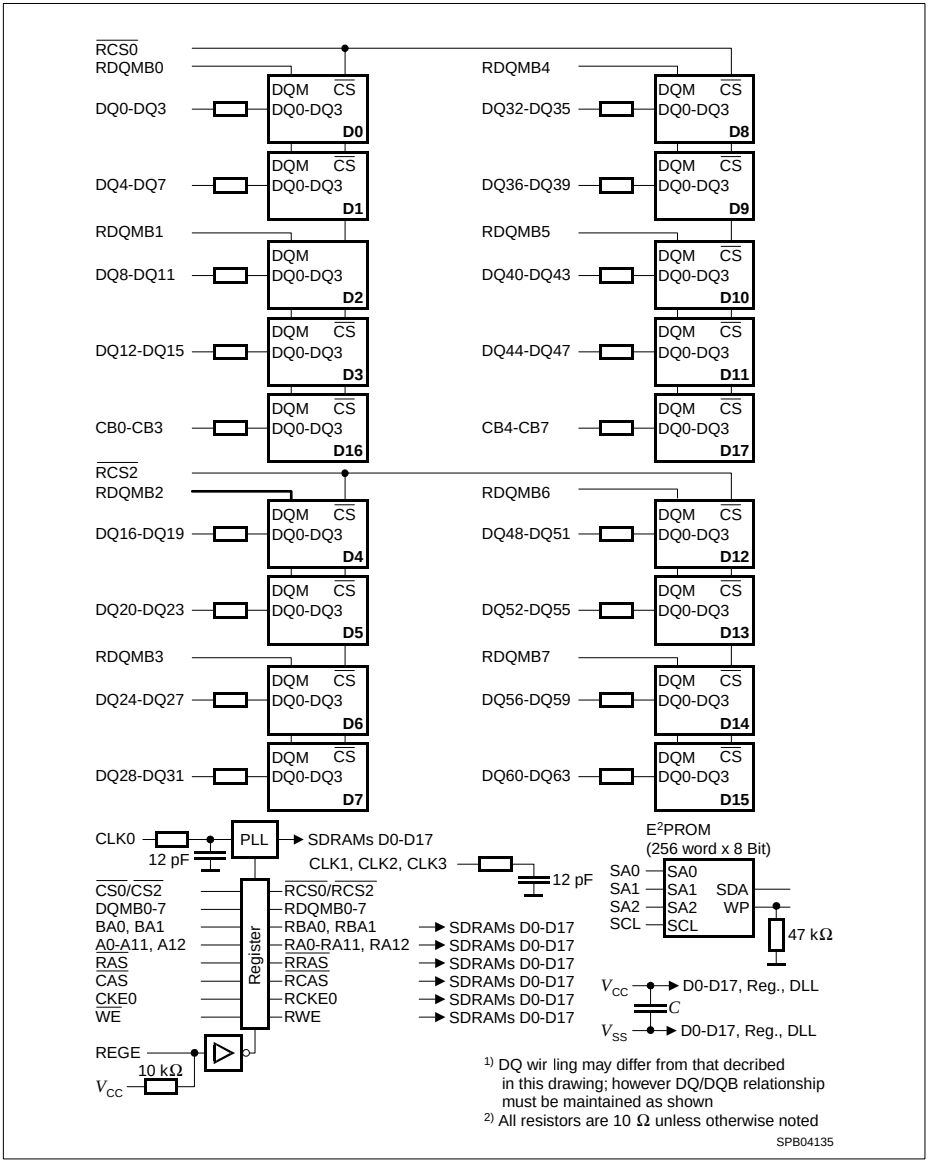
Note : *) To confirm to this specification, motherboards must pull this pin to high state or no connect.

Address Format

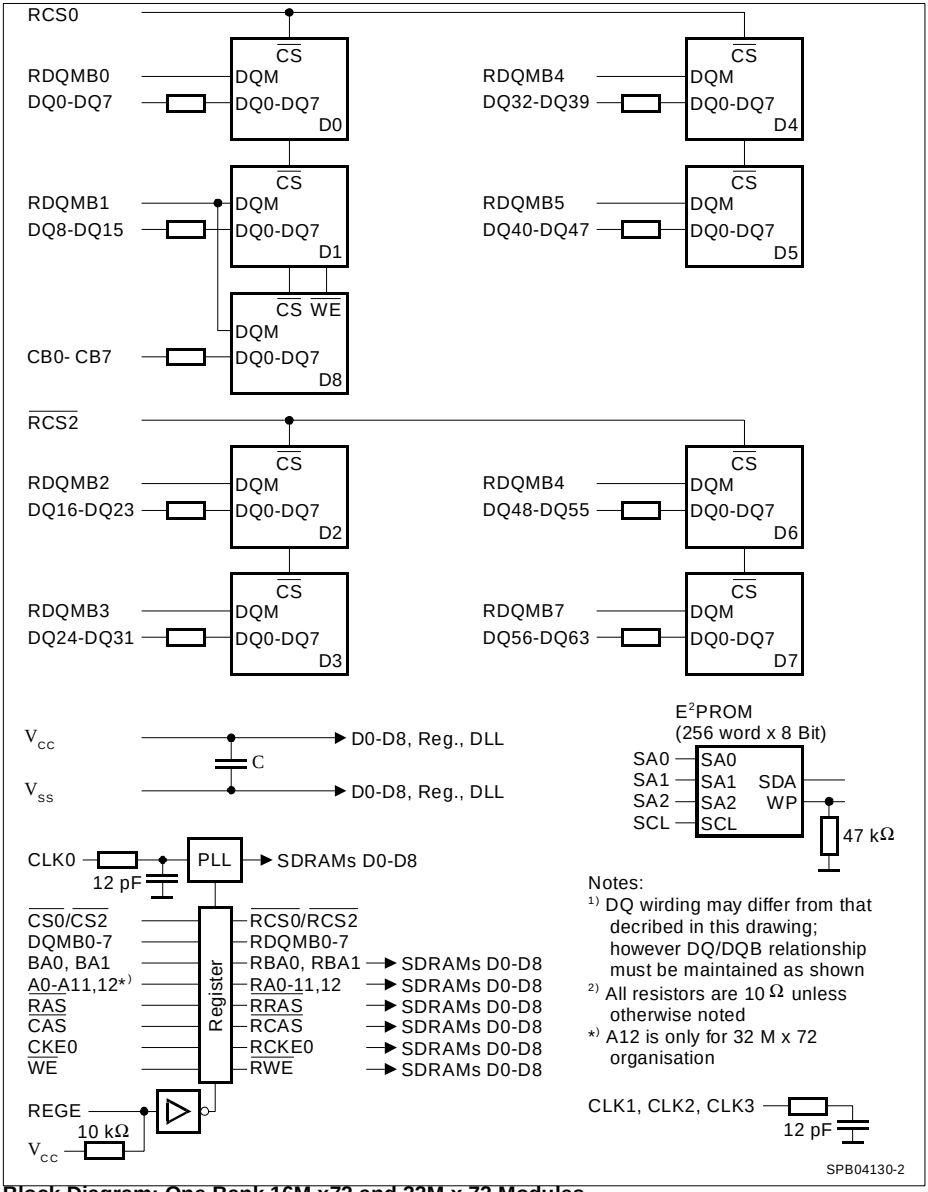
Density	Organization	Memory Banks	SDRAMs	# of SDRAMs	# of row/bank/ columns bits	Refresh	Period	Interval
128 MB	16M × 72	1	16M × 4	18	12/2/10	4k	64 ms	15.6 µs
128 MB	16M × 72	1	16M x 8	9	12/2/10	4k	64 ms	15.6 µs
256 MB	32M x 72	1	32M x 4	18	12/2/11	4k	64 ms	15.6 µs
256 MB	32M x 72	1	32M x 8	9	13/2/10	8k	64 ms	7.8 µs
512 MB	64M × 72	1	64M × 4	18	13/2/11	8k	64 ms	7.8 µs
1 GB	128M × 72	2	64M × 4	36	13/2/11	8k	64 ms	7.8 µs
1 GB	128M × 72	1	128M × 4	18	13/2/12	8k	64ms	7.8 µs
2 GB	256M × 72	2	128M × 4	36	13/2/12	8k	64ms	7.8 µs

Pin Configuration

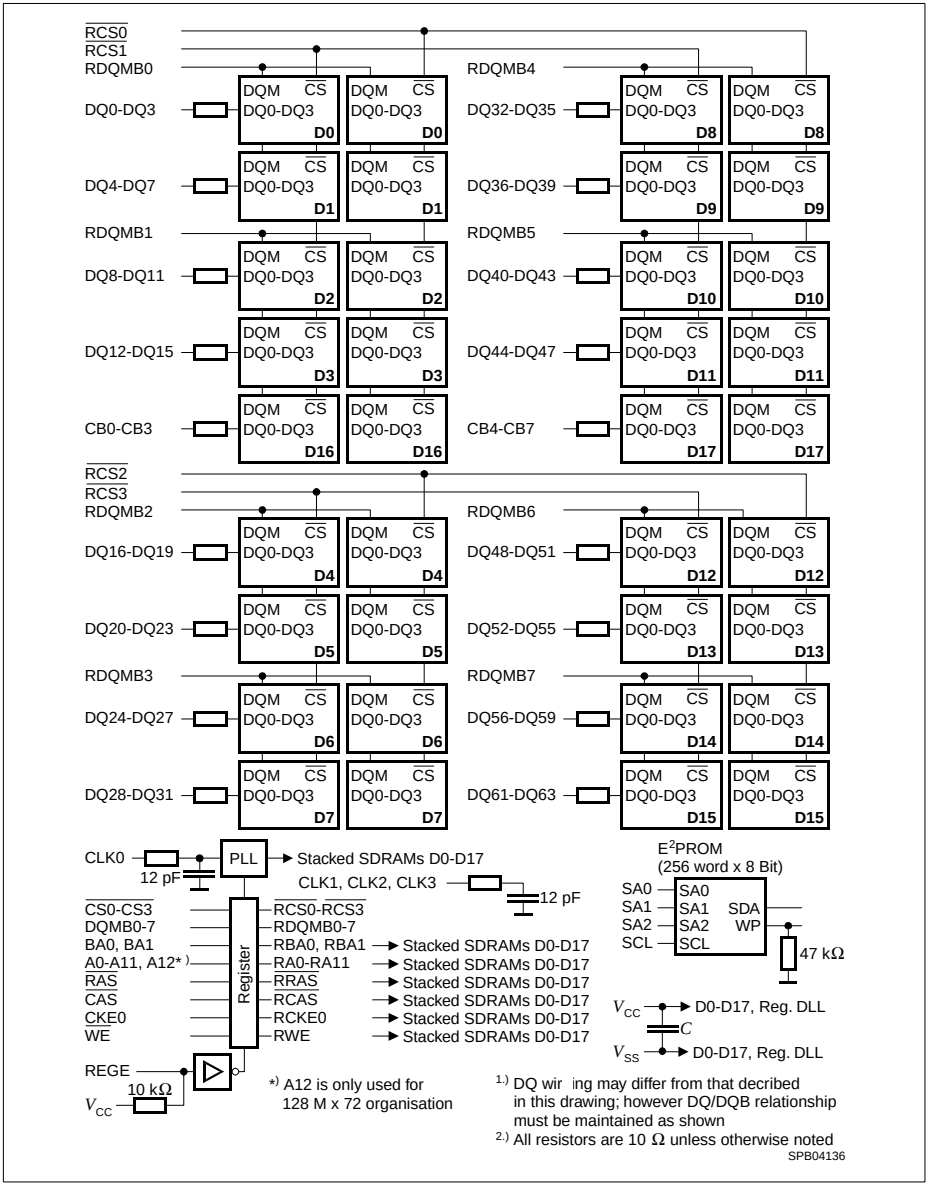
PIN#	Symbol	PIN#	Symbol	PIN#	Symbol	PIN#	Symbol
1	V_{SS}	43	V_{SS}	85	V_{SS}	127	V_{SS}
2	DQ0	44	DU	86	DQ32	128	CKE0
3	DQ1	45	CS2	87	DQ33	129	CS3
4	DQ2	46	DQMB2	88	DQ34	130	DQMB6
5	DQ3	47	DQMB3	89	DQ35	131	DQMB7
6	V_{DD}	48	DU	90	V_{DD}	132	N.C.
7	DQ4	49	V_{DD}	91	DQ36	133	V_{DD}
8	DQ5	50	N.C.	92	DQ37	134	N.C.
9	DQ6	51	N.C.	93	DQ38	135	N.C.
10	DQ7	52	CB2	94	DQ39	136	CB6
11	DQ8	53	CB3	95	DQ40	137	CB7
12	V_{SS}	54	V_{SS}	96	V_{SS}	138	V_{SS}
13	DQ9	55	DQ16	97	DQ41	139	DQ48
14	DQ10	56	DQ17	98	DQ42	140	DQ49
15	DQ11	57	DQ18	99	DQ43	141	DQ50
16	DQ12	58	DQ19	100	DQ44	142	DQ51
17	DQ13	59	V_{DD}	101	DQ45	143	V_{DD}
18	V_{DD}	60	DQ20	102	V_{DD}	144	DQ52
19	DQ14	61	N.C.	103	DQ46	145	N.C.
20	DQ15	62	DU	104	DQ47	146	DU
21	CB0	63	N.C.	105	CB4	147	REGE
22	CB1	64	V_{SS}	106	CB5	148	V_{SS}
23	V_{SS}	65	DQ21	107	V_{SS}	149	DQ53
24	N.C.	66	DQ22	108	N.C.	150	DQ54
25	N.C.	67	DQ23	109	N.C.	151	DQ55
26	V_{DD}	68	V_{SS}	110	V_{DD}	152	V_{SS}
27	WE	69	DQ24	111	CAS	153	DQ56
28	DQMB0	70	DQ25	112	DQMB4	154	DQ57
29	DQMB1	71	DQ26	113	DQMB5	155	DQ58
30	CS0	72	DQ27	114	CS1	156	DQ59
31	DU	73	V_{DD}	115	RAS	157	V_{DD}
32	V_{SS}	74	DQ28	116	V_{SS}	158	DQ60
33	A0	75	DQ29	117	A1	159	DQ61
34	A2	76	DQ30	118	A3	160	DQ62
35	A4	77	DQ31	119	A5	161	DQ63
36	A6	78	V_{SS}	120	A7	162	V_{SS}
37	A8	79	CLK2	121	A9	163	CLK3
38	A10 (AP)	80	N.C.	122	BA0	164	N.C.
39	BA1	81	WP	123	A11	165	SA0
40	V_{DD}	82	SDA	124	V_{DD}	166	SA1
41	V_{DD}	83	SCL	125	CLK1	167	SA2
42	CLK0	84	V_{DD}	126	A12	168	V_{DD}



Block Diagram: One Bank 16M x 72, 32M x 72, 64M x 72 and 128M x 72 SDRAM DIMM Modules HYS72V16300GR, HYS72V32301GR, HYS72V64300GR and HYS72V128320GR using x4 organized SDRAMs



Block Diagram: One Bank 16M x72 and 32M x 72 Modules
HYS72V16301 & HYS72V32300GR using x8 organized SDRAMs



Block Diagram: Two Bank 128M x 72 and 256M x 72 SDRAM DIMM Modules
HYS 72V128320GR and HYS72V256320GR Using Stacked x4 Organized SDRAMs

Absolute Maximum Ratings

Parameter	Symbol	Limit Values		Unit
		min.	max.	
Input / Output voltage relative to V_{SS}	V_{IN}, V_{OUT}	– 1.0	4.6	V
Power supply voltage on V_{DD}	V_{DD}	– 1.0	4.6	V
Storage temperature range	T_{STG}	-55	+150	°C
Power dissipation (per SDRAM component)	P_D	–	1	W
Data out current (short circuit)	I_{OS}	–	50	mA

Permanent device damage may occur if “Absolute Maximum Ratings” are exceeded.
Functional operation should be restricted to recommended operation conditions.
Exposure to higher than recommended voltage for extended periods of time affect device reliability

DC Characteristics
T_A = 0 to 70 °C [1]; V_{SS} = 0 V; V_{DD} = 3.3 V ± 0.3 V

Parameter	Symbol	Limit Values		Unit
		min.	max.	
Input High Voltage	V_{IH}	2.0	V_{DD} + 0.3	V
Input Low Voltage	V_{IL}	– 0.5	0.8	V
Output High Voltage (I_{OUT} = – 4.0 mA)	V_{OH}	2.4	–	V
Output Low Voltage (I_{OUT} = 4.0 mA)	V_{OL}	–	0.4	V
Input Leakage Current, any input (0 V < V_{IN} < 3.6 V, all other inputs = 0 V)	$I_{I(L)}$	– 10	10	µA
Output Leakage Current (DQ is disabled, 0 V < V_{OUT} < V_{DD})	$I_{O(L)}$	– 10	10	µA

Capacitance
T_A = 0 to 70 °C [1]; V_{DD} = 3.3 V ± 0.3 V, f = 1 MHz

Parameter	Symbol	Limit Values		Unit
		One Bank Modules	Two Bank Modules	
Input Capacitance (all inputs except CLK and CKE)	C_{IN}	10	20	pF
Input Capacitance (CLK)	C_{CLK}	30	30	pF
Input Capacitance (CKE)	C_{CKE}	17	30	pF
Input/Output Capacitance(DQ0 - DQ63, CB0 - CB7)	C_{IO}	10	17	pF
Input Capacitance (SCL, SA0 - 2)	C_{SC}	8	8	pF
Input/Output Capacitance (SDA)	C_{SD}	8	8	pF

Operating Currents per SDRAM Component
T_A = 0 to 70 °C [1], V_{DD} = 3.3 V ± 0.3 V

Parameter	Test Condition	Symbol	64 Mb	128 Mb	256 Mb	512 Mb	Unit	Note
			max.					
Operating current $t_{RC} = t_{RC(MIN.)}$, $t_{CK} = t_{CK(MIN.)}$ Outputs open, Burst Length = 4, CL = 3. All banks operated in random access, all banks operated in ping-pong manner to maximize gapless data access	–	I_{CC1}	110	160	270	tbd.	mA	2)
Precharge stand-by current in Power Down Mode $\overline{CS} = V_{IH(MIN.)}$, CKE ≤ $V_{IL(MAX.)}$	t_{CK} = min.	I_{CC2P}	2	1.5	2	tbd.	mA	2)
Precharge Stand-by Current in Non-Power Down Mode $\overline{CS} = V_{IH(MIN.)}$, CKE ≥ $V_{IH(MIN.)}$	t_{CK} = min.	I_{CC2N}	40	40	25	tbd.	mA	2)
No operating current t_{CK} = min., $\overline{CS} = V_{IH(MIN.)}$, active state (max. 4 banks)	CKE ≥ $V_{IH(MIN.)}$	I_{CC3N}	50	50	50	tbd.	mA	2)
	CKE ≤ $V_{IL(MAX.)}$	I_{CC3P}	8	10	10	tbd.	mA	2)
Burst operating current t_{CK} = min., Read command cycling	–	I_{CC4}	70	100	170	tbd.	mA	2), 3)
Auto refresh current t_{CK} = min., Auto Refresh command cycling	–	I_{CC5}	140	230	240	tbd.	mA	2)
Self refresh current Self Refresh Mode,CKE = 0.2 V	–	I_{CC6}	1	1.5	2.5	tbd.	mA	2)

AC Characteristics (SDRAM Device Specification) [4), 5)]
T_A = 0 to 70 °C [1)]; V_{SS} = 0 V; V_{DD} = 3.3 V ± 0.3 V, t_T = 1 ns

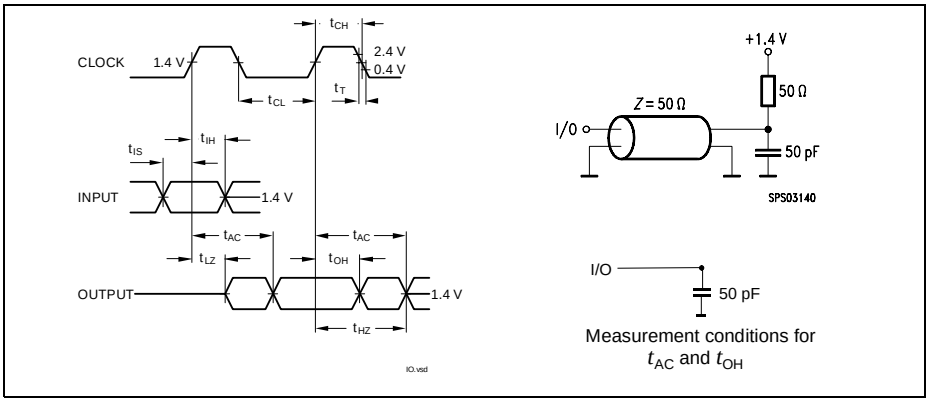
Parameter	Symbol	Limit Values				Unit	Note
		-7 PC133-222		-7.5 PC133-333			
		min.	max.	min.	max.		
Clock and Access Time							
Clock Cycle Time	t_{CK}						–
$\overline{CAS}$ Latency = 3		7.5	–	7.5	–	ns	
$\overline{CAS}$ Latency = 2		7.5	–	10	–	ns	
Clock Frequency	f_{CK}						–
$\overline{CAS}$ Latency = 3		–	133	–	133	MHz	
$\overline{CAS}$ Latency = 2		–	133	–	100	MHz	
Access Time from Clock	t_{AC}						–
$\overline{CAS}$ Latency = 3		–	5.4	–	5.4	ns	
$\overline{CAS}$ Latency = 2		–	5.4	–	6	ns	
Clock High Pulse Width	t_{CH}	2.5	–	2.5	–	ns	–
Clock Low Pulse Width	t_{CL}	2.5	–	2.5	–	ns	–
Transition Time	t_T	0.5	7.5	0.5	10	ns	–
Setup and Hold Parameters							
Input Setup Time	t_{IS}	1.5	–	1.5	–	ns	–
Input Hold Time	t_{IH}	0.8	–	0.8	–	ns	–
Power Down Mode Entry Time	t_{SB}	–	1	–	1	CLK	–
Power Down Mode Exit Setup Time	t_{PDE}	1	–	1	–	CLK	–
Mode Register Setup Time	t_{RCS}	2	–	2	–	CLK	–
Common Parameters							
Row to Column Delay Time	t_{RCD}	15	–	20	–	ns	–
Row Precharge Time	t_{RP}	15	–	20	–	ns	–
Row Active Time	t_{RAS}	37	–	45	100k	ns	–
Row Cycle Time	t_{RC}	60	–	67.5	–	ns	–
Activate (a) to Activate (b) Command Period	t_{RRD}	2	–	2	–	CLK	–
$\overline{CAS}$(a) to $\overline{CAS}$(b) Command Period	t_{CCD}	1	–	1	–	CLK	–

AC Characteristics (SDRAM Device Specification) (cont'd) [4), 5)]
T_A = 0 to 70 °C [1)]; V_{SS} = 0 V; V_{DD} = 3.3 V ± 0.3 V, t_T = 1 ns

Parameter	Symbol	Limit Values				Unit	Note
		-7 PC133-222		-7.5 PC133-333			
		min.	max.	min.	max.		
Refresh Cycle							
Refresh Period 64&128MBit SDRAM Based Modules 256&512MBit SDRAM Based Modules	t_{REF}	 – –	 15.6 7.8	 – –	 15.6 7.8	 µs µs	–
Self Refresh Exit Time	t_{SREX}	1	–	1	–	CLK	[6)]
Read Cycle							
Data Out Hold Time	t_{OH}	3	–	3	–	ns	–
Data Out to Low Impedance Time	t_{LZ}	0	–	0	–	ns	[7)]
Data Out to High Impedance Time	t_{HZ}	3	7	3	7	ns	[7)]
DQM Data Out Disable Latency	t_{DQZ}	–	2	–	2	CLK	–
Write Cycle							
Data Input to Precharge (write recovery)	t_{WR}	2	–	2	–	CLK	–
DQM Write Mask Latency	t_{DQW}	0	–	0	–	CLK	–

Notes

1. The registered DIMM modules are designed to operate under system operating conditions between 0-55 deg C ambient, maximum sustained bandwidth and 0 LFM airflow. Operating at higher ambient temperatures needs sufficient air flow to limit the case temperature of the SDRAM components do not exceed 85°C.
2. These parameters depend on the cycle rate. All values are measured at 133 MHz operation frequency. Input signals are changed once during tck excepts for Icc6 and for standby currents when tck = infinity.
3. These parameters are measured with continous data stream during read access and all DQ toggling. CL=3 and BL=4 is assumed and the data-out current is excluded.
4. An initial pause of 100 µs is required after power-up. Then a Precharge All Banks command must be given followed by eight Auto Refresh (CBR) cycles before the Mode Register Set Operation can begin. Also the on-DIMM PLL must be given enough clock cycles to stabilize (t_{STAB}) before any operation can be guaranteed.
5. AC timing tests have V_{IL} = 0.8 V and V_{IH} = 2.0 V with the timing referenced to the 1.4 V crossover point. The transition time is measured between V_{IH} and V_{IL}. All AC measurements assume t_T = 1 ns with the AC output load circuit shown. Specified t_{AC} and t_{OH} parameters are measured with a 50 pF only, without any resistive termination and with a input signal of 1 V/ns edge rate between 0.8 V and 2.0 V.
6. Self Refresh Exit is a synchronous operation and begins on the second positive clock edge after CKE returns high. Self Refresh Exit is not complete until a time period equal to t_{RC} is satisfied after the Self Refresh Exit command is registered.
7. Referenced to the time at which the output achieves the open circuit condition, not to output voltage levels.



Serial Presence Detect

A serial presence detect storage device - E^{2}PROM 34C02 - is assembled onto the module. Information about the module configuration, speed, etc. is written into the E^{2}PROM device during module production using a serial presence detect protocol (I^{2}C synchronous 2-wire bus).The first 128 bytes are utilized by the DIMM manufacturer and the second 128 bytes are available to the end user.

SPD-Table for -7.5 Registered DIMM Modules

Byte#	Description	SPD Entry Value	Hex							
			128 MB 1 Bank 1)	128 MB 1 Bank 2)	256 MB 1 Bank 3)	256 MB 1 Bank 4)	512 MB 1 Bank	1 GB 2 Banks	1 GB 1 Bank	2 GB 2 Banks
0	Number of SPD Bytes	128	80							
1	Total Bytes in Serial PD	256	08							
2	Memory Type	SDRAM	04							
3	Number of Row Addresses	12/13	0C	0C	0C	0D	0D	0D	0D	0D
4	Number of Column Addresses	10/11/12	0A	0A	0B	0A	0B	0B	0C	0C
5	Number of DIMM Banks	1/2	01	01	01	01	01	02	01	02
6	Module Data Width	72	48							
7	Module Data Width (cont'd)	0	00							
8	Module Interface Levels	LVTTL	01							
9	Cycle Time at CL = 3	7.5 ns	75							
10	Access Time from Clock at CL = 3	5.4 ns	54							
11	DIMM Config (Error Det/Corr.)	ECC	02							
12	Refresh Rate/Type	15.6/7.8 µs	80	80	80	82	82	82	82	82
13	SDRAM Width, Primary	x4 / x8	04	08	04	08	04	04	04	04
14	Error Checking SDRAM Data Width	x4 / x8	04	08	04	08	04	04	04	04
15	Minimum t_{CCD}	1 CLK	01							
16	Burst Length Supported	1, 2, 4, 8 & (full page)	8F	0F	0F	0F	0F	0F	0F	0F
17	Number of SDRAM Banks	4	04							
18	SDRAM Supported CAS Latencies	2 & 3	06							
19	SDRAM $\overline{CS}$ Latencies	0	01							
20	SDRAM WE Latencies	0	01							
21	SDRAM DIMM Module Attributes	with PLL	1F							
22	SDRAM Device Attributes	V_{DD} tol +/– 10%	0E							
23	Min. Clock Cycle Time at CL = 2	10 ns	A0							
24	Max. Data Access Time from Clock for CL = 2	6.0 ns	60							
25	Min. Clock Cycle Time at CL = 1	not supported	00							
26	Max. Data Access Time from Clock at CL = 1	not supp.	00							
27	SDRAM Minimum t_{RP}	20 ns	14							
28	SDRAM Minimum t_{RRD}	15 ns	0F							
29	SDRAM Minimum t_{RCD}	20 ns	14							
30	SDRAM Minimum t_{RAS}	45 ns	2D							

SPD-Table for -7.5 Registered DIMM Modules (cont'd)

Byte#	Description	SPD Entry Value	Hex							
			128 MB 1 Bank 1)	128 MB 1 Bank 2)	256 MB 1 Bank 3)	256 MB 1 Bank 4)	512 MB 1 Bank	1 GB 2 Banks	1 GB 1 Bank	2 GB 2 Banks
31	Module Bank Density (per bank)	128 MByte 256 Mbyte 512 MByte 1 GByte	20	20	40	40	80	80	01	01
32	SDRAM Input Setup Time	1.5 ns	15							
33	SDRAM Input Hold Time	0.8 ns	08							
34	SDRAM Data Input Setup Time	1.5 ns	15							
35	SDRAM Data Input Hold Time	0.8 ns	08							
36-61	Superset Information (may be used in future)	–	00							
62	SPD Revision	JEDEC 2	12							
63	Checksum for Bytes 0 - 62	–	D8	60	79	83	BC	BD	3E	3F
64-125	Manufacturer's Information	–								
126	Frequency Specification	–	64							
127	Details of Clocks	–	8F							
128+	Unused Storage Locations	–	FF							

1) HYS72V16300GR-7.5
2) HYS72V16301GR-7.5
3) HYS72V32301GR-7.5
4) HYS72V32300GR-7.5

SPD-Table for -7 Registered DIMM Modules

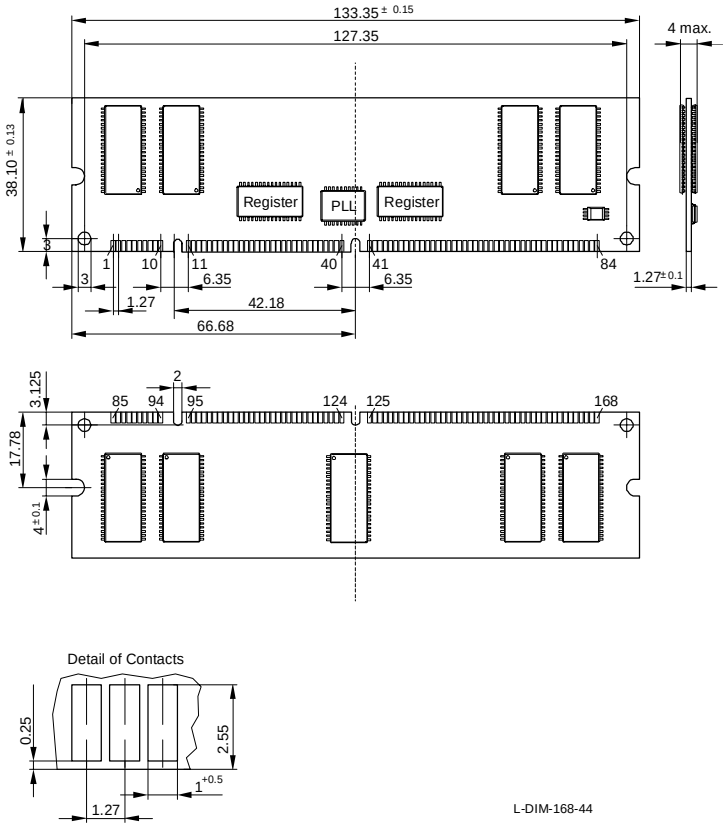
Byte#	Description	SPD Entry Value	Hex							
			128 MB 1 Bank 1)	128 MB 1 Bank 2)	256 MB 1 Bank 3)	256 MB 1 Bank 4)	512 MB 1 Bank	1 GB 2 Banks	1 GB 1 Bank	2 GB 2 Banks
0	Number of SPD Bytes	128	80							
1	Total Bytes in Serial PD	256	08							
2	Memory Type	SDRAM	04							
3	Number of Row Addresses	12/13	0C	0C	0C	0D	0D	0D	0D	0D
4	Number of Column Addresses	10/11/12	0A	0A	0B	0A	0B	0B	0C	0C
5	Number of DIMM Banks	1/2	01	01	01	01	01	02	01	02
6	Module Data Width	72	48							
7	Module Data Width (cont'd)	0	00							
8	Module Interface Levels	LVTTL	01							
9	Cycle Time at CL = 3	7.5 ns	75							
10	Access Time from Clock at CL = 3	5.4 ns	54							
11	DIMM Config (Error Det/Corr.)	ECC	02							
12	Refresh Rate/Type	15.6/7.8 µs	80	80	80	82	82	82	82	82
13	SDRAM Width, Primary	x4 / x8	04	08	04	08	04	04	04	04
14	Error Checking SDRAM Data Width	x4 / x8	04	08	04	08	04	04	04	04
15	Minimum t_{CCD}	1 CLK	01							
16	Burst Length Supported	1, 2, 4, 8 & (full page)	8F	0F	0F	0F	0F	0F	0F	0F
17	Number of SDRAM Banks	4	04							
18	SDRAM Supported $\overline{CAS}$ Latencies	2 & 3	06							
19	SDRAM $\overline{CS}$ Latencies	0	01							
20	SDRAM $\overline{WE}$ Latencies	0	01							
21	SDRAM DIMM Module Attributes	with PLL	1F							
22	SDRAM Device Attributes	V_{DD} tol +/– 10%	0E							
23	Min. Clock Cycle Time at CL = 2	7.5 ns	75							
24	Max. Data Access Time from Clock for CL = 2	5.6 ns	54							
25	Min. Clock Cycle Time at CL = 1	not supported	00							
26	Max. Data Access Time from Clock at CL = 1	not supp.	00							
27	SDRAM Minimum t_{RP}	15 ns	0F							
28	SDRAM Minimum t_{RRD}	14 ns	0E							
29	SDRAM Minimum t_{RCD}	15 ns	0F							
30	SDRAM Minimum t_{RAS}	37 ns	25							

Byte#	Description	SPD Entry Value	Hex							
			128 MB 1 Bank 1)	128 MB 1 Bank 2)	256 MB 1 Bank 3)	256 MB 1 Bank 4)	512 MB 1 Bank	1 GB 2 Banks	1 GB 1 Bank	2 GB 2 Banks
31	Module Bank Density (per bank)	128 MByte 256 Mbyte 512 MByte 1024 MByte	20	20	40	40	80	80	01	01
32	SDRAM Input Setup Time	1.5 ns	15							
33	SDRAM Input Hold Time	0.8 ns	08							
34	SDRAM Data Input Setup Time	1.5 ns	15							
35	SDRAM Data Input Hold Time	0.8 ns	08							
36-61	Superset Information (may be used in future)	–	00							
62	SPD Revision	JEDEC 2	12							
63	Checksum for Bytes 0 - 62	–	8E	16	2F	39	72	73	F4	F5
64-125	Manufacturer's Information	–								
126	Frequency Specification	–	64							
127	Details of Clocks	–	8F							
128+	Unused Storage Locations	–	FF							

1) HYS72V16300GR-7
2) HYS72V16301GR-7
3) HYS72V32301GR-7
4) HYS72V32300GR-7

Package Outlines for Raw Card AA

Module Package
JEDEC MO-161
Registered DIMM Modules Raw Card AA (L-DIM168-44)

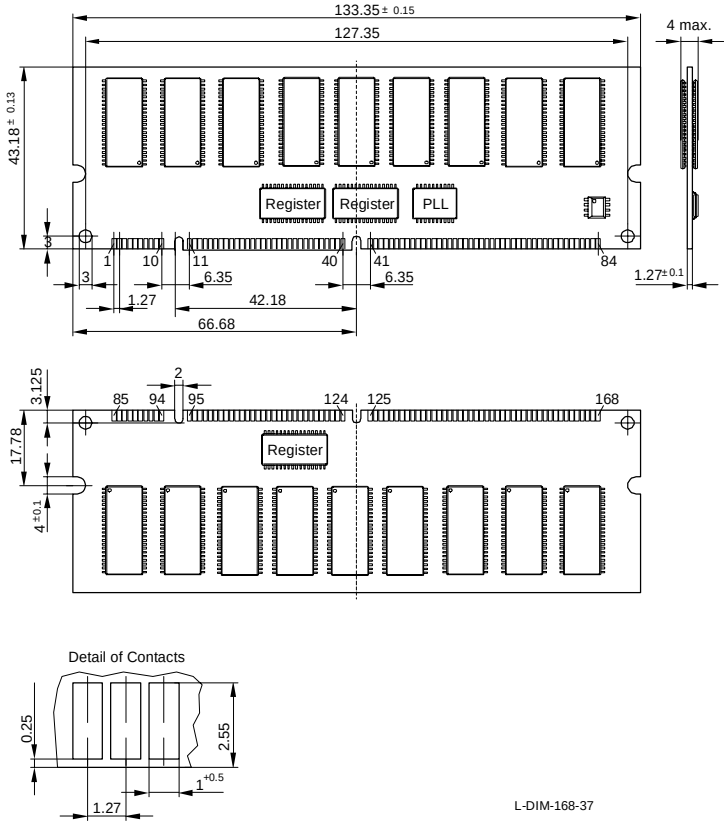


note: all outline dimensions and tolerances are in accordance with the JEDEC standard

Package Outlines for Raw Card B

Module Package
JEDEC MO-161
Registered DIMM Modules Raw Card B (L-DIM168-37)

128MB, 256MB, 512MB & 1GB modules based on
x4 SDRAM components

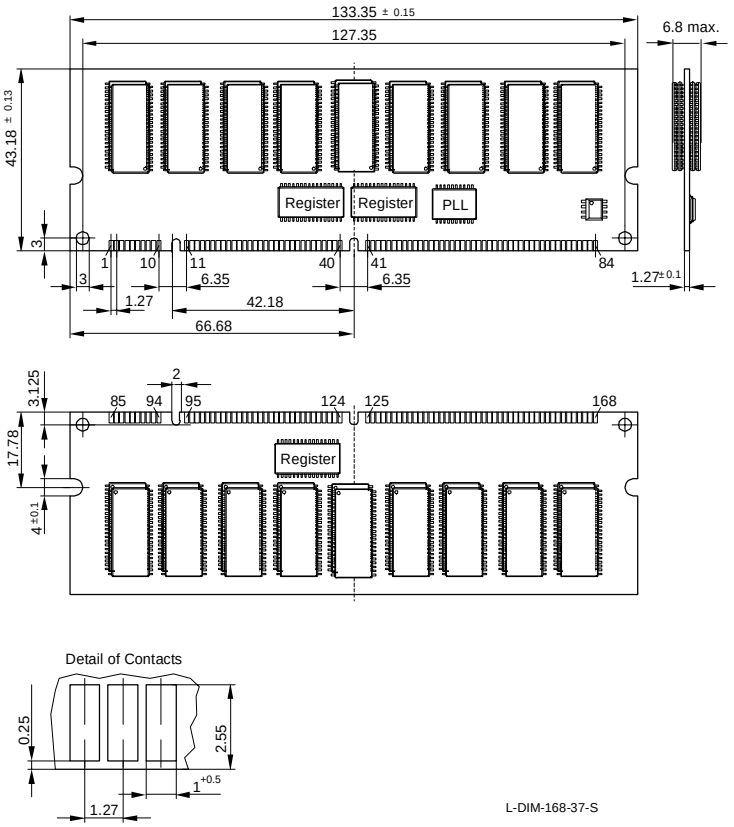


note: all outline dimensions and tolerances are in accordance with the JEDEC standard

Package Outlines for Raw Card B (with stacked components)

Module Package
JEDEC MO-161
Registered DIMM Modules Raw Card B (L-DIM168-37)

1 GByte and 2 GByte modules



note: all outline dimensions and tolerances are in accordance with the JEDEC standard

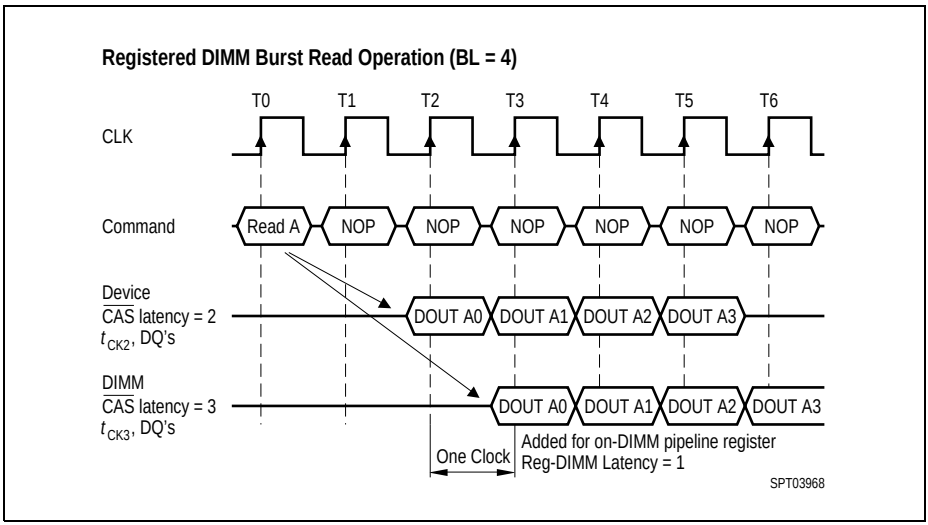
Functional Description

All these PC133 168-pin Registered DIMMs conform to a compatible set of timing and operation characteristics intended to comply with the 133 MHz standards. The Registered DIMMs achieve high speed data transfer rate up to 133 MHz, when in “registered mode”. The “registered mode” is achieved when the REGE input signal is in “high” state or the pin is not connected. Operation in “buffered mode” (REGE = “low”) needs careful system design to compensate all input signals for the extra delay time of the register components when in “buffered mode”. “Buffered mode” is limited to 66 Mhz maximum operation frequency.

Registered Mode:

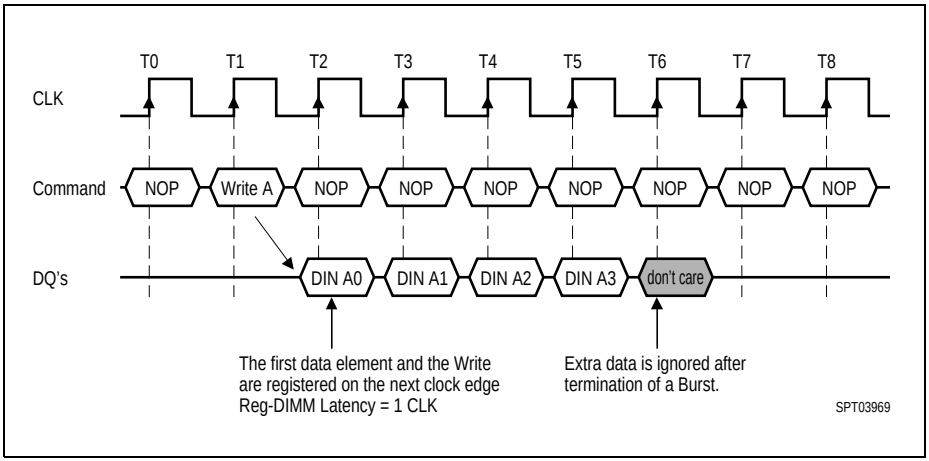
All control and address signals are synchronized with the positive edge of externally supplied clocks and are registered on-DIMM and hence delayed by one clock cycle in arriving at the SDRAM devices. The use of the on-board register reduces the capacitive loading of the DIMM on input control and address signals. The SDRAM device data lines (DQ) are connected directly to the DIMM tabs through 10 Ohm series resistors. All the following timing diagrams and explanations show DIMM operation at the tabs, not SDRAM operation.

The picture below depicts an overview of the effect of the Registered Mode on the data outputs (DQs) for a Read operation. Without the registers, the data is delayed according to the device $\overline{\text{CAS}}$ latency, in the case two clocks. With the register, the data is delayed according to the device $\overline{\text{CAS}}$ latency plus an additional clock cycle. This is known as the DIMM $\overline{\text{CAS}}$ latency, and in this example is four three. The data path can be thought of as a pipeline in which the register effectively lengthens the pipe by one clock cycle.



In case of a Burst Write Command the data-in is delayed one clock due the op-DIMM pipeline register also. Therefore, data for the first Burst Write cycle must be applied on the DQ pins on the next clock cycle after the Write command is issued. the remaining data inputs must be supplied on

each subsequent rising clock edge until the burst length is completed. When the burst has finished, any additional data supplied to the DQ pins will be ignored.



Registered DIMM Burst Write Operation (BL = 4)

Change List

1.99	First revision
2.99	Iol & Ioh changed to 4 mA, Input capacitances on CLK adjusted to 12 PF according to INTEL Rev.1.2 registered DIMM specification, thz max changed to 7 ns
2.99	Compliance Coded adjusted in accordance JEDEC PC133 Rev.0.9 specification
2.99	Byte 21 changed from 16 to 1F according to JEDEC PC133 Rev.0.9 spec.
4.99	Changed to final Infineon logo added
6.5.99	Some SPD codes changed for PC100 2-2-2 compartibility
25.5.99	512 Mbyte and 1GB PC133 DIMM added
15.7.99	Partnumber changes from HYS72Vxx200GR to HYS72Vxx300GR due to new gerber file L-DIMM168-37-2 CL2 condition for 256Mb based modules changed from -8(222) to -8A(322)
5.8.99	256MByte module based on 128 Mbit SDRAMs added
31.8.99	Drawings for Raw Card B added
6.9.99	Databookversion from R+L used, 256MByte added
1.10.99	Checksum for 128Mb based module added some typoos corrected, Headline changed
8.11.99	Thickness dimensions for 1 GByte module drawing changed to 8 max.
30.11.99	Notes renumbered, note 1 added : Registered DIMM module operating temperature conditions, some parameters changed according to INTELs PC133 specifiction
13.12.99	HYS72V32300GR-7.5 (256Mbit based 256Mbyte module added)
10.1.2000	HYS72V16301GR-7.5 added
25.9.2000	ICC currents on page 9 updated according to the latest values of the 64M S19, 128Mb S17 and 256Mb S20 datasheet
4.12.2000	Thickness for 1 GByte modules changed from 8.00 mm max.(JEDEC) to 6,40 typ. (actual)
18.1.2001	Clarification of “buffered mode”operation as a not tested functionality on these modules. Datasheet is for PC133 Registered DIMMs with components based on S17 process and further shrink versions only Changes in SPD-Code for 256Mb based modules in Byte 23, 127 and the Check sum in Byte 63 to make these module 100 % backward compatible to PC100-2-2-2 operation (TPCR_05 from 19.01.2001)
14.02.2001	-7 speed sort (PC133-222) added SPD Codes for -7 added
3.4.2001	2 GByte Module added
6.6.2001	Typo in SPB04130 corrected (new: SPB04130-2) Outline drawings changed to L-DIM-168-44, 37 & 37S Absolute maximum rating table added
06.09.2001	1GByte module one bank with 512Mbit component added 1 GByte and 2 Gbyte modules with “inhouse” stacking added SCR: Thickness of modules with stacked components changed from 6.4 to 6.8 max
19.9.2001	1 GByte and 2 Gbyte modules with “inhouse” stacking added
17.12.2001	SCR-028-2001-11-12 PC133 / TPCR_08 / JC42.5 Item 1138.5 : JEDEC changed Byte 62h (SPD Revision) from 02h to 12h Checksum changed therefore also